TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK2549

DC-DC Converter, Relay Drive and Motor Drive Applications

• 2.5 V gate drive

• Low drain—source ON resistance $: R_{DS (ON)} = 0.29 \Omega \text{ (typ.)}$ • High forward transfer admittance $: |Y_{fs}| = 3.0 \text{ S (typ.)}$ • Low leakage current $: I_{DSS} = 100 \text{ } \mu\text{A (max) (V}_{DS} = 16 \text{ V)}$

• Enhancement-mode : $V_{th} = 0.5 \sim 1.1 \text{ V (VDS} = 10 \text{ V, ID} = 200 \mu\text{A})$

Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	16	V	
Drain-gate voltage (Ro	_{GS} = 20 kΩ)	V_{DGR}	16	V	
Gate-source voltage		V_{GSS}	±8	V	
Drain current	DC (Note 1)	I _D	2	Α	
	Pulse (Note 1)	I _{DP}	6	^	
Drain power dissipation	n	P_{D}	0.5	W	
Drain power dissipation (Note 2)		P_{D}	1.5	W	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: Mounted on ceramic substrate (25.4 mm × 25.4 mm × 0.8 mm)

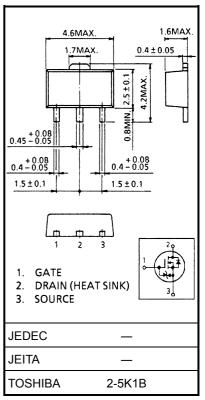
Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient	R _{th (ch-a)}	250	°C/W

This transistor is an electrostatic sensitive device.

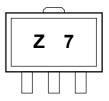
Please handle with caution.

Unit: mm



Weight: 0.05 g (typ.)

Marking



(The two digits represent the part number.)



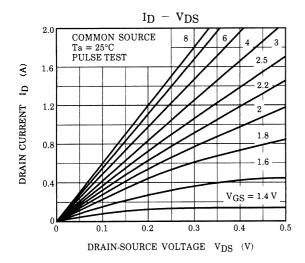
Electrical Characteristics (Ta = 25°C)

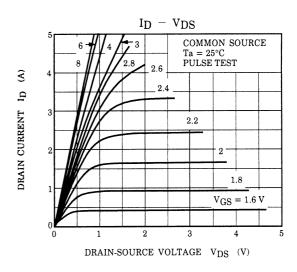
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±6.5 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 16 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	16	_	_	V
Gate threshold v	oltage/	V_{th}	V _{DS} = 10 V, I _D = 200 μA	0.5	_	1.1	V
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 2.5 V, I _D = 0.5 A	_	0.29	0.38	Ω
			V _{GS} = 4 V, I _D = 1 A	1	0.22	0.29	32
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 1 A	1.5	3.0	_	S
Input capacitano	e	C _{iss}		_	260	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	34	_	pF
Output capacitance		Coss		_	103	_	
Switching time	Rise time	t _r	$V_{GS} \stackrel{5}{\underset{0}{\text{ V}}} V \stackrel{I_{D} = 1 \text{ A}}{\underset{\sim}{\text{V}}} V_{OUT}$ $R_{L} = 8 \Omega$ $V_{DD} \stackrel{\vdots}{=} 8 V$	_	200	_	
	Turn-on time	t _{on}		_	250	_	ne
	Fall time	t _f		_	300	_	ns ns
	Turn-off time	t _{off}	Duty \leq 1%, $t_{\rm w} = 10 \mu \rm s$	_	800	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	5.0		
Gate-source charge		Q _{gs}	$V_{DD} \approx 16 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 2 \text{ A}$		3.2		nC
Gate-drain ("miller") charge		Q _{gd}			1.8		

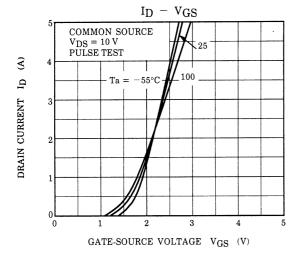
Source-Drain Ratings and Characteristics (Ta = 25°C)

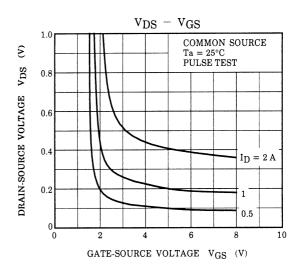
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	2	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	6	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 2 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 2 A, V _{GS} = 0 V		220	_	ns
Reverse recovered charge	Q _{rr}	dI _{DR} / dt = 50 A / μs	_	0.32	_	μC

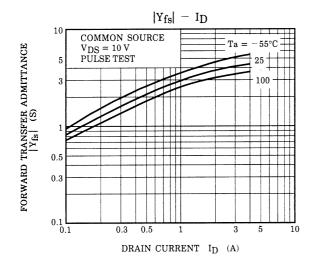
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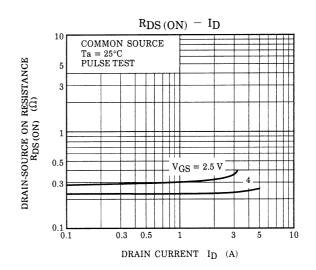




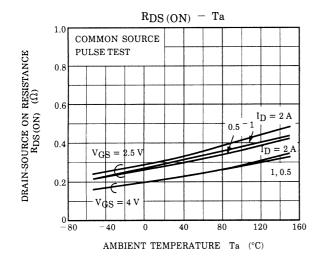


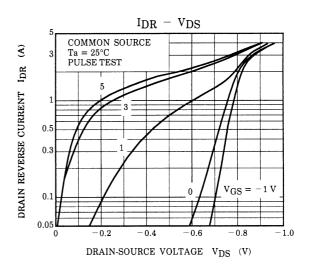


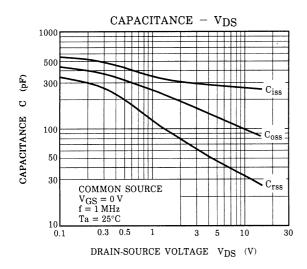


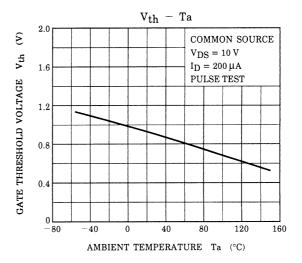


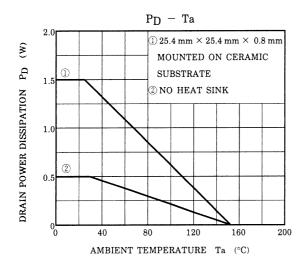
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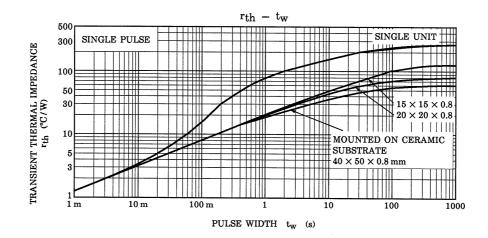


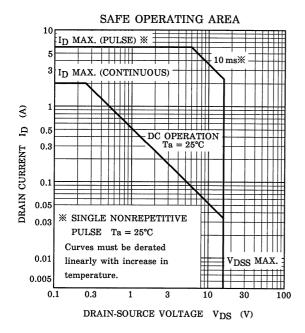






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